



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hisashi Ohtani Art Unit : 1765
Serial No.: 09/596,755 Examiner : Robert Kunemund
Filed : June 15, 2000
Title : MANUFACTURING METHOD OF SEMICONDUCTOR AND
 MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

BOX AF

Commissioner for Patents
Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Official Action dated April 3, 2001,
Paper No. 6, in the above-referenced application, please amend
the above-identified application as follows:

In the Claims:

Please amend claims 2, 8, 14, 20, 22, 29, 36, and 41 as
follows:

2. (Amended) A method for manufacturing a semiconductor
device comprising steps of:

forming a semiconductor film over a substrate; and

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Thereby certify under 37 CFR §1.8(a) that this correspondence is being
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Susan Regan